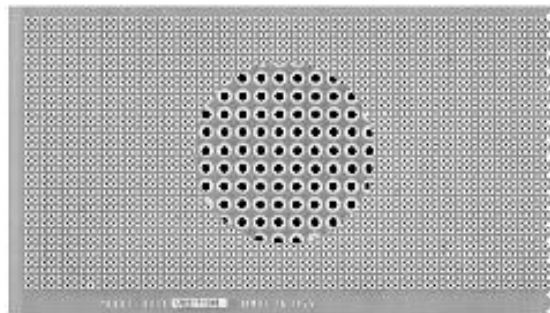


## 8010 4.0" x 13.0"

**Circuit Pattern:** Pad-Per-Hole  
**Contacts:** N/A  
**Width/Thick:** 12.86"/.062"  
**Height:** 4.00"  
**Contacts:** N/A  
**16-Pin DIP Capacity:** 124  
**Material:** FR4 Epoxy Glass  
**Wire-Wrap Terminals:** T44, T46, T49, T68,  
**Solder Terminals:** T42-1  
**Wire-Wrap Socket Pins:** R32  
**Hole Diameter:** .042"

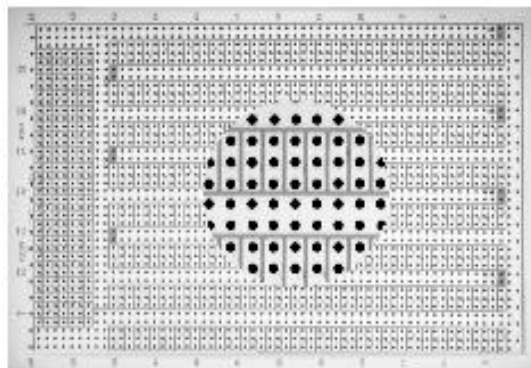
- Precision-Drilled, plated-thru holes
- 0.080" diameter, isolated solder pad around each hole
- Board size and surface area approximate Macintosh II specifications
- Unrestricted component placement



## 8001 4.50" x 6.5"

**Circuit Pattern:** 3-Hole Solder Pad  
**Contacts:** N/A  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 20  
**Material:** CEM-1  
**Solder Terminals:** T42-1, K24C, K31C  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Hole Diameter:** .042"

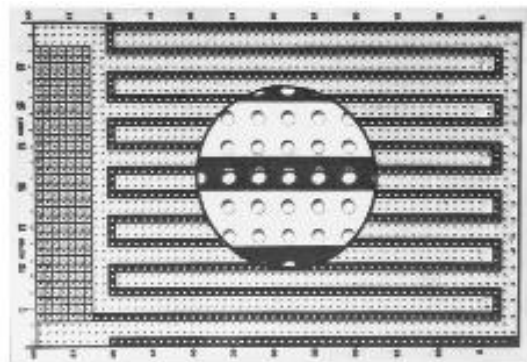
- Circuit pattern etched onto wiring side only
- Solder mount DIP sockets or IC devices with any lead spacing
- 3-hole solder pads (0.28" X 0.080") for interconnecting multiple component leads



## 8002 4.5" x 6.5"

**Circuit Pattern:** Interleaved Buses  
**Contacts:** N/A  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 36  
**Material:** CEM-1  
**Solder Terminals:** T42-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Hole Diameter:** .042"

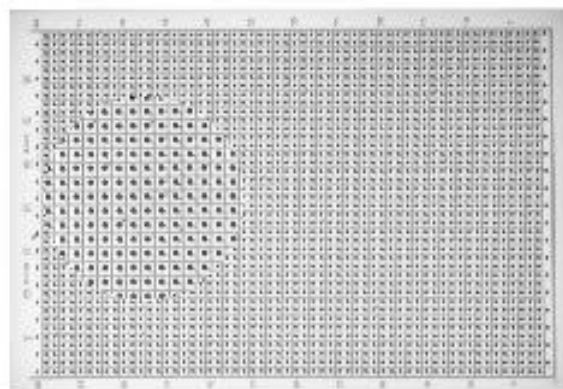
- Ideal for wire-wrap applications
- Power and ground buses etched onto wiring side only
- Bus surfaces solder coated for user convenience
- Mount components with 0.3", 0.6" and 0.9" lead spacing
- I/O area with solder pads for mounting connector

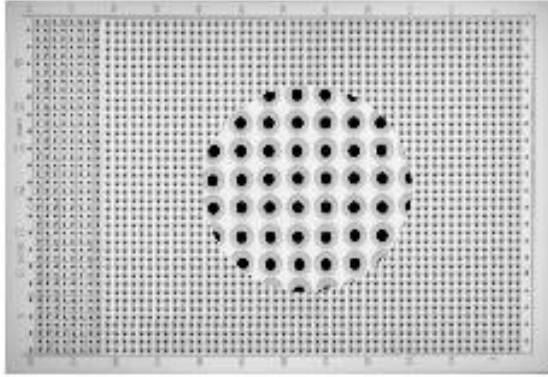


## 8003 4.5" x 6.5"

**Circuit Pattern:** Pad-Per-Hole  
**Contacts:** N/A  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 60  
**Material:** CEM-1  
**Solder Terminals:** T42-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Hole Diameter:** .042"

- Square solder pad etched around each hole on wiring side
- Accommodates any type DIP IC device or discrete component

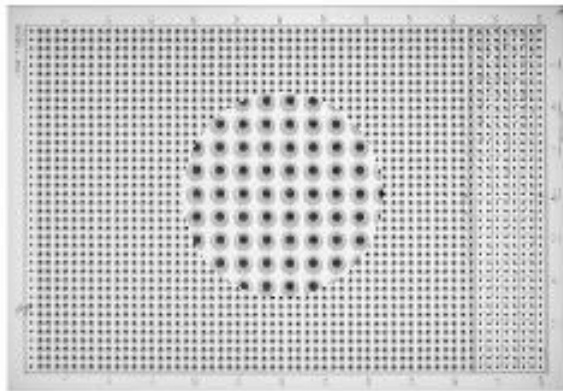




**8004 4.5" x 6.5"**

**Circuit Pattern:** Ground Plane  
**Contacts:** N/A  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 50  
**Material:** CEM-1  
**Solder Terminals:** T42-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Hole Diameter:** .042"

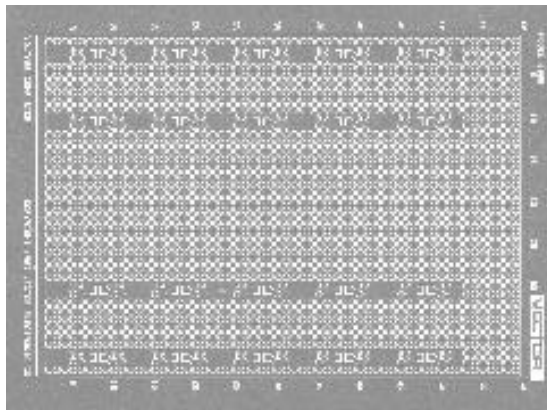
- To commit wire-wrap pins to voltage and ground planes, use Vector T124 solder washers, available separately
- 0.085" diameter clearance around holes
- Etched overall ground plane on wiring side only
- Plane surfaces solder-coated for user convenience
- I/O area with solder pads for mounting connector



**8007 4.5" x 6.5"**

**Circuit Pattern:** Pad-Per-Hole/  
Ground Plane  
**Contacts:** N/A  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 60  
**Material:** CEM-1  
**Solder Terminals:** T42-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Hole Diameter:** .042"

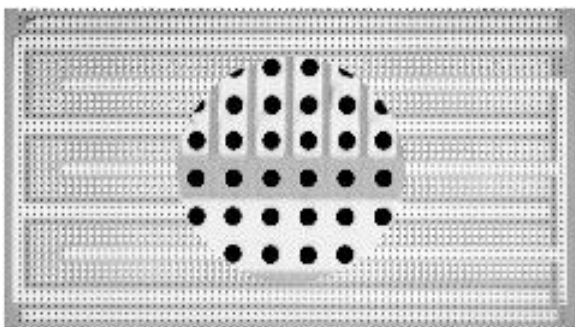
- Pad-Per-Hole pattern on component side - overall Ground Plane pattern on wiring side
- To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately
- 0.080" diameter, isolated solder pad around holes, component side
- Accommodates any type DIP IC device or discrete component
- Plane and pad surfaces solder-coated for user convenience



**8008 4.5" x 6.5"**

**Circuit Pattern:** Pads & Planes  
**Contacts:** N/A  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 70  
**Material:** FR4 Epoxy Glass  
**Solder Terminals:** T42-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Hole Diameter:** .042"

- Unique circuit pattern features full voltage and ground planes on opposite sides with isolated, plated-thru holes
- 0.080" diameter, isolated solder pad around holes, component side
- Plane surfaces solder-coated for user convenience
- SMD cap positions for discrete decoupling capacitors



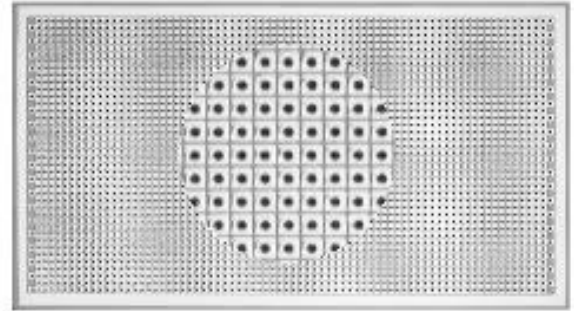
**3677-6 4.5" x 8.08"**

**Circuit Pattern:** 3-Hole Solder Pad  
**Contacts:** N/A  
**Width/Thick:** 8.08"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 21  
**Material:** CEM-1  
**Solder Terminals:** T42-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Hole Diameter:** .042"

- Etched circuit pattern on wiring side only
- 0.080" diameter, isolated solder pad around holes, both sides
- 3-hole solder pads (0.028" X 0.080") for interconnecting multiple component leads
- Pad and bus surfaces solder-coated for user convenience

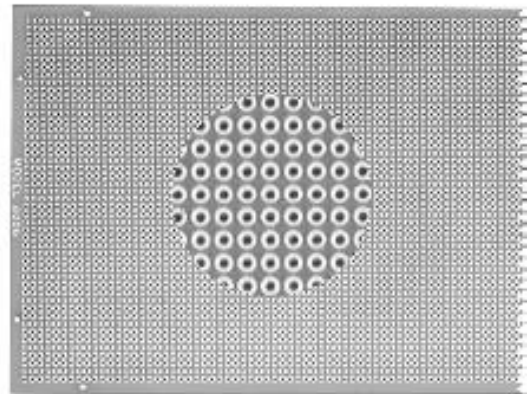
## 45P80-1 4.5" x 8.08"

<b>Circuit Pattern:</b>	Pad-Per-Hole	
<b>Contacts:</b>	N/A	
<b>Width/Thick:</b>	8.08"/.062"	• Isolated, square pads around each hole
<b>Height:</b>	4.50"	
<b>16-Pin DIP Capacity:</b>	80	
<b>Material:</b>	CEM-1	
<b>Solder Terminals:</b>	T42-1	
<b>Wire-Wrap Terminals:</b>	T44, T46, T49, T68	
<b>Wire-Wrap Socket Pins:</b>	R32	
<b>Hole Diameter:</b>	.042"	



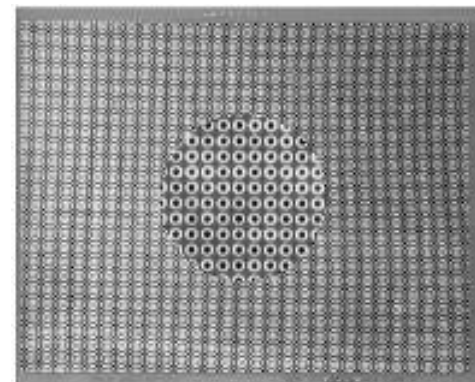
## 8006 5.0" x 13.25"

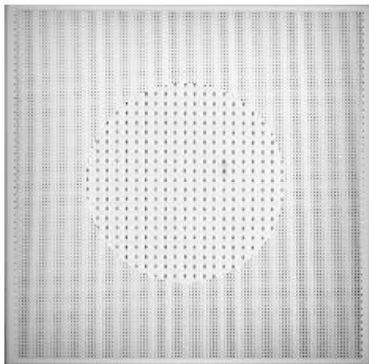
<b>Circuit Pattern:</b>	Pad-Per-Hole	
<b>Contacts:</b>	N/A	
<b>Width/Thick:</b>	13.25"/.062"	• Copper plated-thru holes
<b>Height:</b>	5.00"	• 0.080" diameter, isolated solder pad around holes, both sides
<b>16-Pin DIP Capacity:</b>	154	• Unrestricted component placement, extended area for high density applications
<b>Material:</b>	FR4 Epoxy Glass	• Board can be cut down into smaller units
<b>Solder Terminals:</b>	T42-1	
<b>Wire-Wrap Terminals:</b>	T44, T46, 49, T68	
<b>Wire-Wrap Socket Pins:</b>	R32	
<b>Hole Diameter:</b>	.042"	



## 8012 9.2" x 11.0"

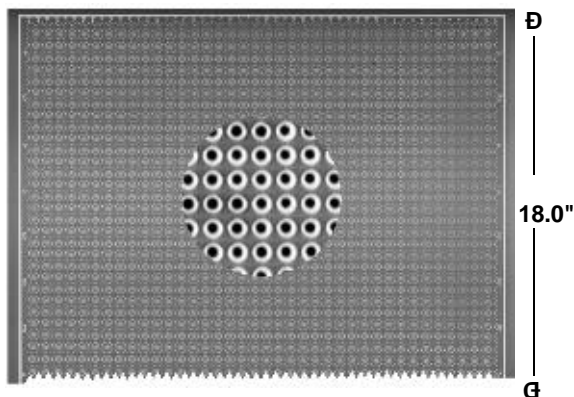
<b>Circuit Pattern:</b>	Pad-Per-Hole	
<b>Contacts:</b>	N/A	
<b>Width/Thick:</b>	11.00"/.062"	• Plated-thru holes
<b>Height:</b>	9.20"	• Approximates Eurocard (DIN) specifications: 6U x 280MM, can be sheared down to 6U x 220MM, or 160MM
<b>16-Pin DIP Capacity:</b>	283	• 0.080" diameter, isolated solder pad around holes
<b>Material:</b>	FR4 Epoxy Glass	• Unrestricted component placement, extended area for high density applications
<b>Solder Terminals:</b>	T42-1	
<b>Wire-Wrap Terminals:</b>	T44, T46, T49, T68	
<b>Wire-Wrap Socket Pins:</b>	R32	
<b>Hole Diameter:</b>	.042"	





### 106P106-1 10.6" x 10.6"

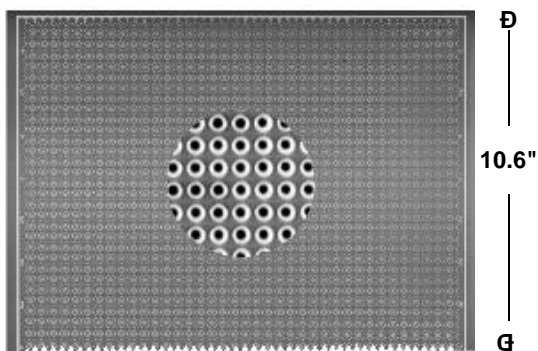
<b>Circuit Pattern:</b>	Pad-Per-Hole	
<b>Contacts:</b>	N/A	
<b>Width/Thick:</b>	10.60"/.062"	
<b>Height:</b>	10.60"	• 0.080" diameter, isolated solder pad around each hole, both sides
<b>16-Pin DIP Capacity:</b>	275	
<b>Material:</b>	FR4 Epoxy Glass	
<b>Solder Terminals:</b>	T42-1	
<b>Wire-Wrap Terminals:</b>	T44, T46, T49, T68	
<b>Wire-Wrap Socket Pins:</b>	R32	
<b>Hole Diameter:</b>	.042"	



### 106P180-4 10.6" X 18.0"

<b>Circuit Pattern:</b>	Pad-Per-Hole & Ground Plane,	
	2 sides	• Individual pads with plated-thru holes
<b>Contacts:</b>	N/A	
<b>Width/Thick:</b>	10.60"/.062"	• Etched ground plane surrounds pads on both sides
<b>Height:</b>	18.00	
<b>16-Pin DIP Capacity:</b>	400	• 0.080" diameter, isolated solder pad around each hole, both sides
<b>Material:</b>	FR4 Epoxy Glass	
<b>Solder Terminals:</b>	T42	
<b>Wire-Wrap Terminals:</b>	T44, T46, T49, T68	
<b>Wire-Wrap Socket Pins:</b>	R32	
<b>Hole Diameter:</b>	.042"	

### 106P70-4 7.0" x 10.6"



<b>Circuit Pattern:</b>	Pad-Per-Hole & Ground Plane	
	N/A	• Individual pads with plated-thru holes
<b>Contacts:</b>	N/A	
<b>Width/Thick:</b>	7.0"/.062"	• Etched ground plane surrounds pads on both sides
<b>Height:</b>	10.60"	
<b>16-Pin DIP Capacity:</b>	175	• 0.080" diameter, isolated solder pad around each hole, both sides
<b>Material:</b>	FR4 Epoxy Glass	
	2 sides	
<b>Solder Terminals:</b>	T42-1	
<b>Wire-Wrap Terminals:</b>	T44, T46, T49, T68	
<b>Wire-Wrap Socket Pins:</b>	R32	
<b>Hole Diameter:</b>	.042"	

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